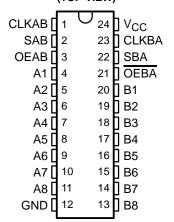
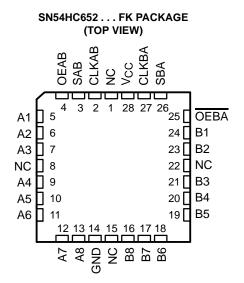
- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 11 ns
- ±6-mA Output Drive at 5 V

SN54HC652...JT OR W PACKAGE SN74HC652...DW OR NT PACKAGE (TOP VIEW)



- Low Input Current of 1 μA Max
- Independent Registers and Enables for A and B Buses
- Multiplexed Real-Time and Stored Data
- True Data Paths



NC - No internal connection

description/ordering information

The 'HC652 devices consist of bus-transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. Output-enable (OEAB and OEBA) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select real-time or stored-data transfer. A low input level selects real-time data, and a high input level selects stored data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with these devices.

ORDERING INFORMATION

TA	PACK	AGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – NT Tube 40°C to 85°C Tube		SN74HC652NT	SN74HC652NT
–40°C to 85°C	SOIC - DW	Tube	SN74HC652DW	HC652
	SOIC - DW	Tape and reel	SN74HC652DWR	HC052
	CDIP – JT		SNJ54HC652JT	SNJ54HC652JT
−55°C to 125°C	CFP – W	Tube	SNJ54HC652W	SNJ54HC652W
	LCCC – FK	Tube	SNJ54HC652FK	SNJ54HC652FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SN54HC652, SN74HC652 **OCTAL BUS TRANSCEIVERS AND REGISTERS** WITH 3-STATE OUTPUTS

SCLS151E - DECEMBER 1982 - REVISED MARCH 2003

description/ordering information (continued)

Data on the A or B data bus, or both, can be stored in the internal D-type flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) terminals, regardless of the select- or output-control terminals. When SAB and SBA are in the real-time transfer mode, it is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. When all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last state.

To ensure the high-impedance state during power up or power down, OEBA should be tied to V_{CC} through a pullup resistor, and OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

FUNCTION TABLE

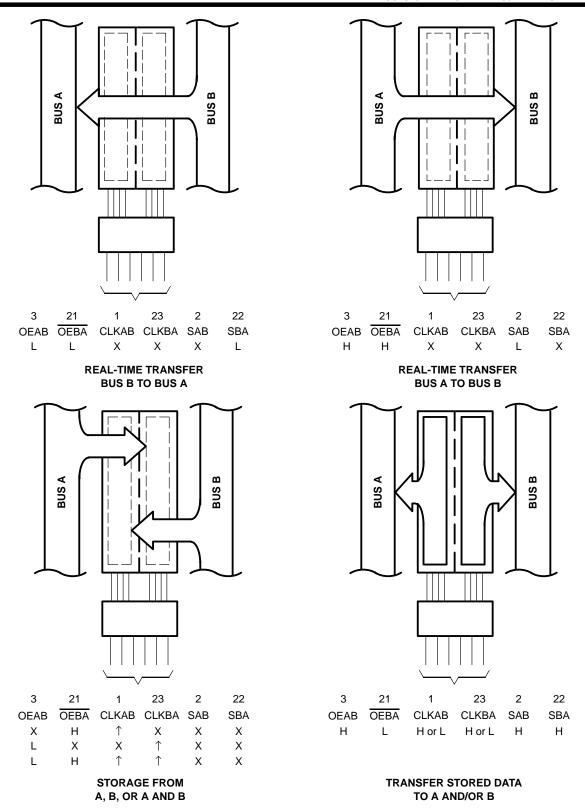
		INPU ⁻	гѕ			DATA	y 1/0‡	OPERATION OR FUNCTION
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1–A8	B1-B8	OPERATION OR FUNCTION
L	Н	H or L	H or L	Х	Х	Input	Input	Isolation
L	Н	\uparrow	\uparrow	X	X	Input	Input	Store A and B data
Х	Н	↑	H or L	Х	Х	Input	Unspecified [‡]	Store A, hold B
Н	Н	\uparrow	\uparrow	X‡	X	Input	Output	Store A in both registers
L	Х	H or L	1	Х	Х	Unspecified [‡]	Input	Hold A, store B
L	L	\uparrow	1	X	X ‡	Output	Input	Store B in both registers
L	L	Χ	Х	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	X	Н	Output	Input	Stored B data to A bus
Н	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
Н	Н	H or L	Χ	Н	X	Input	Output	Stored A data to B bus
Н	L	H or L	H or L	Н	Н	Output	Output	Stored A data to B bus and stored B data to A bus

The data-output functions are enabled or disabled by a variety of level combinations at OEAB or OEBA. Data-input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition on the clock inputs.



[‡] Select control = L: clocks can occur simultaneously.

Select control = H: clocks must be staggered to load both registers.

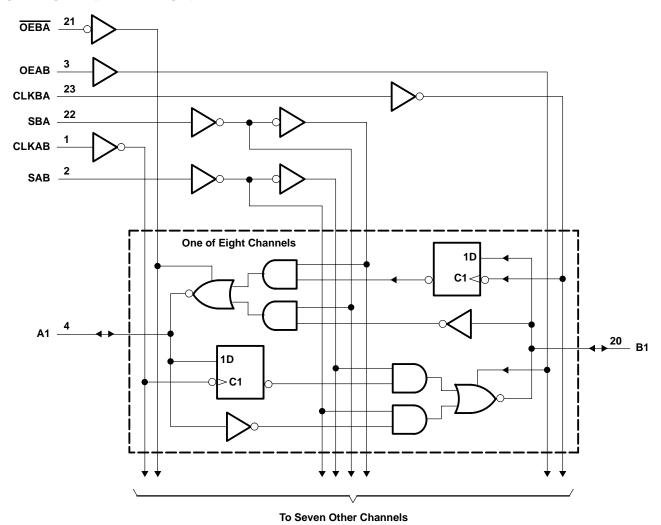


Pin numbers shown are for the DW, JT, NT, and W packages.

Figure 1. Bus-Management Functions



logic diagram (positive logic)



Pin numbers shown are for the DW, JT, NT, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{CC}) (see Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±35 mA
Continuous current through V _{CC} or GND	±70 mA
Package thermal impedance, θ _{JA} (see Note 2): DW package	46°C/W
(see Note 3): NT package	
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-3.



recommended operating conditions (see Note 4)

			SN	154HC65	52	SN	174HC65	2	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
ViH	High-level input voltage	V _{CC} = 4.5 V	3.15		7	3.15			V
		VCC = 6 V	4.2		<.	4.2			
		V _{CC} = 2 V		PEL	0.5			0.5	
VIL	Low-level input voltage	V _{CC} = 4.5 V		2	1.35			1.35	V
		VCC = 6 V		0	1.8			1.8	
٧ı	Input voltage		0	7	VCC	0		VCC	V
۷o	Output voltage		0		VCC	0		VCC	V
		V _{CC} = 2 V			1000			1000	
t _t	Input transition (rise and fall) time	V _{CC} = 4.5 V			500			500	ns
		VCC = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAD	AMETED	TEST OF	NOTIONS		Т	A = 25°C	;	SN54H	C652	SN74F	IC652	LINIT
PAR	AMETER	lesi co	ONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
				2 V	1.9	1.998		1.9		1.9		
			I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4		
VOH		VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
			$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
			$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2	i'h	5.34		
				2 V		0.002	0.1		0.1		0.1	
			$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1	<	0.1		0.1	
V_{OL}		$V_I = V_{IH}$ or V_{IL}		6 V		0.001	0.1	ć	0.1		0.1	V V nA μA μA
			I _{OL} = 6 mA	4.5 V		0.17	0.26	20	0.4		0.33	
			I _{OL} = 7.8 mA	6 V		0.15	0.26	% 0	0.4		0.33	
II	Control inputs	$V_I = V_{CC}$ or 0		6 V		±0.1	±100	4	±1000		±1000	nA
loz	A or B	VO = VCC or GN	D	6 V		±0.01	±0.5		±10		±5	μΑ
Icc	-	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci	Control inputs			2 V to 6 V		3	10		10		10	pF

SN54HC652, SN74HC652 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

SCLS151E - DECEMBER 1982 - REVISED MARCH 2003

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	T _A = 1	25°C	SN54F	IC652	SN74H	IC652	UNIT
		VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNII
		2 V		6		4.3		5.5	
fclock	Clock frequency	4.5 V		31		22		27	MHz
		6 V		36		25		31	
		2 V	80		115	, N	95		
t _W	Pulse duration, CLKBA or CLKAB high or low	4.5 V	16		23	77	19		ns
		6 V	14		20		16		
		2 V	100		150		125		
t _{su}	Setup time, A before CLKAB↑ or B before CLKBA↑	4.5 V	20		30		25		ns
		6 V	17		26		21		
		2 V	5		5		5		
th	Hold time, A after CLKAB↑ or B after CLKBA↑	4.5 V	5		5		5		ns
		6 V	5		5		5		

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 2)

242445752	FROM	то		T,	4 = 25°C	;	SN54F	IC652	SN74F	IC652	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	6	10		4.3		5.5		
f _{max}			4.5 V	31	40		22		27		MHz
			6 V	36	45		25		31		
			2 V		65	180		270		225	
	CLKBA or CLKAB	A or B	4.5 V		18	36		54		45	
			6 V		14	31		46		38	
			2 V		50	135		205		170	
^t pd	A or B	B or A	4.5 V		14	27		41		34	ns
			6 V		11	23		35		29	
			2 V		70	190	4	285		240	
	SBA or SAB†	A or B	4.5 V		20	38	25	57		48	
			6 V		16	32	0	48		41	
			2 V		85	245	0	370		305	
t _{en}	OEBA or OEAB	A or B	4.5 V		25	49		74		61	ns
			6 V		20	42		63		52	
			2 V		50	245		370		305	
^t dis	OEBA or OEAB	A or B	4.5 V		23	49		74		61	ns
			6 V		20	42		63		52	
			2 V		28	60		90		75	
t _t		Any	4.5 V		8	12		18		15	ns
			6 V		6	10		15		13	

[†] These parameters are measured with the internal output state of the storage register opposite that of the bus input.



switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 2)

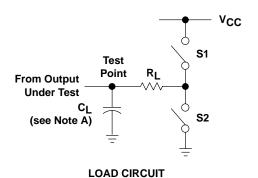
PARAMETER	FROM	то	V	T,	գ = 25°C	;	SN54H	IC652	SN74H	C652	UNIT
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
			2 V		90	265		400		330	
	CLKBA or CLKAB	A or B	4.5 V		24	53		80		66	
			6 V		18	46		68		57	
			2 V		70	220		335		275	
t _{pd}	A or B	B or A	4.5 V		20	44		70		55	ns
			6 V		15	38		57		48	
			2 V 80 275			6	415		345		
	SBA or SAB†	A or B	4.5 V		24	55	70	83		69	
			6 V		20	47	50	70		60	
			2 V		100	330	Q	500		410	
t _{en}	OEBA or OEAB	A or B	4.5 V		33	66		100		82	ns
			6 V		27	57		85		71	
			2 V		45	210		315		265	
t _t		Any	4.5 V		17	42		63		53	ns
			6 V		13	36		53		43	

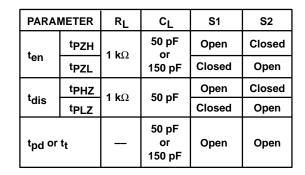
[†] These parameters are measured with the internal output state of the storage register opposite that of the bus input.

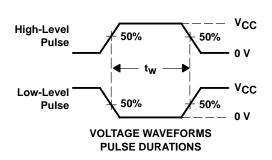
operating characteristics, $T_A = 25^{\circ}C$

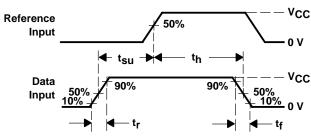
	PARAMETER	TEST CONDITIONS	TYP	UNIT
Γ	C _{pd} Power dissipation capacitance	No load	50	pF

PARAMETER MEASUREMENT INFORMATION

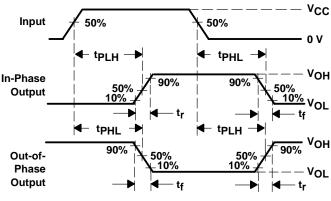


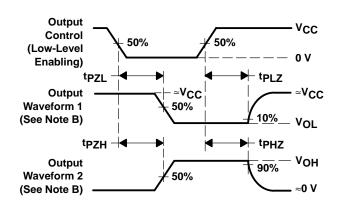






VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns.
- D. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLz and tpHz are the same as tdis.
- G. tpZL and tpZH are the same as ten.
- H. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN74HC652DW	Obsolete	Production	SOIC (DW) 24	-	-	Call TI	Call TI	-40 to 85	HC652
SN74HC652DWR	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC652
SN74HC652DWR.A	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC652

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC652DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 16-Apr-2024



*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
I	SN74HC652DWR	SOIC	DW	24	2000	350.0	350.0	43.0

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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